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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	ARM® Cortex®-M0
Core Size	32-Bit Single-Core
Speed	72MHz
Connectivity	CANbus, I²C, IrDA, LINbus, SmartCard, SPI, UART/USART, USB
Peripherals	Brown-out Detect/Reset, DMA, I²S, LVD, POR, PS2, PWM, WDT
Number of I/O	45
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	4K x 8
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	2.5V ~ 5.5V
Data Converters	A/D 7x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	64-LQFP
Supplier Device Package	64-LQFP (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/nuvoton-technology-corporation-america/nuc240sc2ae

LIST OF FIGURES

2.2 NuMicro™ NUC240 Features – Connectivity Line

- ARM® Cortex™-M0 core
  - Runs up to 72 MHz
  - One 24-bit system timer
  - Supports low power sleep mode
  - Single-cycle 32-bit hardware multiplier
  - NVIC for the 32 interrupt inputs, each with 4-levels of priority
  - Serial Wire Debug supports with 2 watchpoints/4 breakpoints
- Built-in LDO for wide operating voltage ranges from 2.5 V to 5.5 V
- Flash Memory
  - 32K/64K/128K bytes Flash for program code
  - 8 KB flash for ISP loader
  - Supports In-System-Program (ISP) and In-Application-Program (IAP) application code update
  - 512 byte page erase for flash
  - Configurable Data Flash address and size for 128 KB system, fixed 4 KB Data Flash for the 32 KB and 64 KB system
  - Supports 2-wired ICP update through SWD/ICE interface
- SRAM Memory
  - 8K/16K bytes embedded SRAM
  - Supports PDMA mode
- PDMA (Peripheral DMA)
  - Supports 9 channels PDMA for automatic data transfer between SRAM and peripherals
  - Supports CRC calculation with four common polynomials, CRC-CCITT, CRC-8, CRC-16 and CRC-32
- Clock Control
  - Flexible selection for different applications
  - Built-in 22.1184 MHz high speed oscillator for system operation
    - Trimmed to ±1 % at +25 ℃ and V_{DD} = 5 V
    - Trimmed to ±3 % at -40 ℃ ~ +105 ℃ and V_{DD} = 2.5 V ~ 5.5 V
  - Built-in 10 kHz low speed oscillator for Watchdog Timer and Wake-up operation
  - Supports one PLL, up to 72 MHz, for high performance system operation
  - External 4~24 MHz high speed crystal input for USB and precise timing operation
  - External 32.768 kHz low speed crystal input for RTC function and low power system operation
- GPIO
  - Four I/O modes:
    - Quasi-bidirectional
    - Push-pull output
    - Open-drain output
    - Input only with high impendence
  - TTL/Schmitt trigger input selectable
  - I/O pin configured as interrupt source with edge/level setting
- Timer
  - Supports 4 sets of 32-bit timers with 24-bit up-timer and one 8-bit prescale counter
  - Independent clock source for each timer
  - Provides one-shot, periodic, toggle and continuous counting operation modes
  - Supports event counting function
  - Supports input capture function
- Watchdog Timer
  - Multiple clock sources
  - 8 selectable time-out period from 1.6 ms ~ 26.0 sec (depending on clock source)
  - Wake-up from Power-down or Idle mode
  - Interrupt or reset selectable on watchdog time-out
  - Supports 4 selectable Watchdog Timer reset delay period(1026, 130, 18 or 3 WDT_CLK)

3 ABBREVIATIONS

Acronym	Description
ACMP	Analog Comparator Controller
ADC	Analog-to-Digital Converter
AES	Advanced Encryption Standard
APB	Advanced Peripheral Bus
AHB	Advanced High-Performance Bus
BOD	Brown-out Detection
CAN	Controller Area Network
DAP	Debug Access Port
DES	Data Encryption Standard
EBI	External Bus Interface
EPWM	Enhanced Pulse Width Modulation
FIFO	First In, First Out
FMC	Flash Memory Controller
FPU	Floating-point Unit
GPIO	General-Purpose Input/Output
HCLK	The Clock of Advanced High-Performance Bus
HIRC	22.1184 MHz Internal High Speed RC Oscillator
HXT	4~24 MHz External High Speed Crystal Oscillator
IAP	In Application Programming
ICP	In Circuit Programming
ISP	In System Programming
LDO	Low Dropout Regulator
LIN	Local Interconnect Network
LIRC	10 kHz internal low speed RC oscillator (LIRC)
MPU	Memory Protection Unit
NVIC	Nested Vectored Interrupt Controller
PCLK	The Clock of Advanced Peripheral Bus
PDMA	Peripheral Direct Memory Access
PLL	Phase-Locked Loop
PWM	Pulse Width Modulation
QEI	Quadrature Encoder Interface
SDIO	Secure Digital Input/Output
SPI	Serial Peripheral Interface

SPS	Samples per Second
TDES	Triple Data Encryption Standard
TMR	Timer Controller
UART	Universal Asynchronous Receiver/Transmitter
UCID	Unique Customer ID
USB	Universal Serial Bus
WDT	Watchdog Timer
WWDT	Window Watchdog Timer

Table 3-1 List of Abbreviations

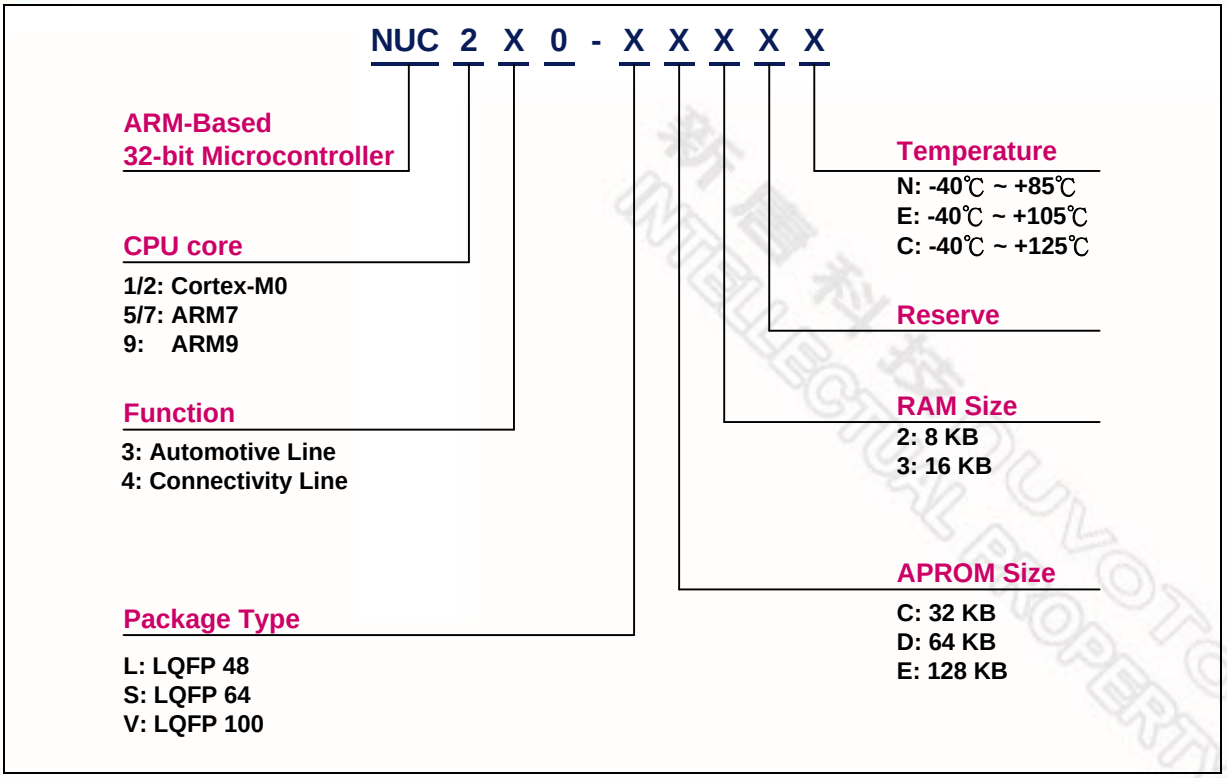

Figure 4-1 NuMicro™ NUC230/240 Series Selection Code

4.2.2.2 NuMicro™ NUC240SxxAE LQFP 64 pin

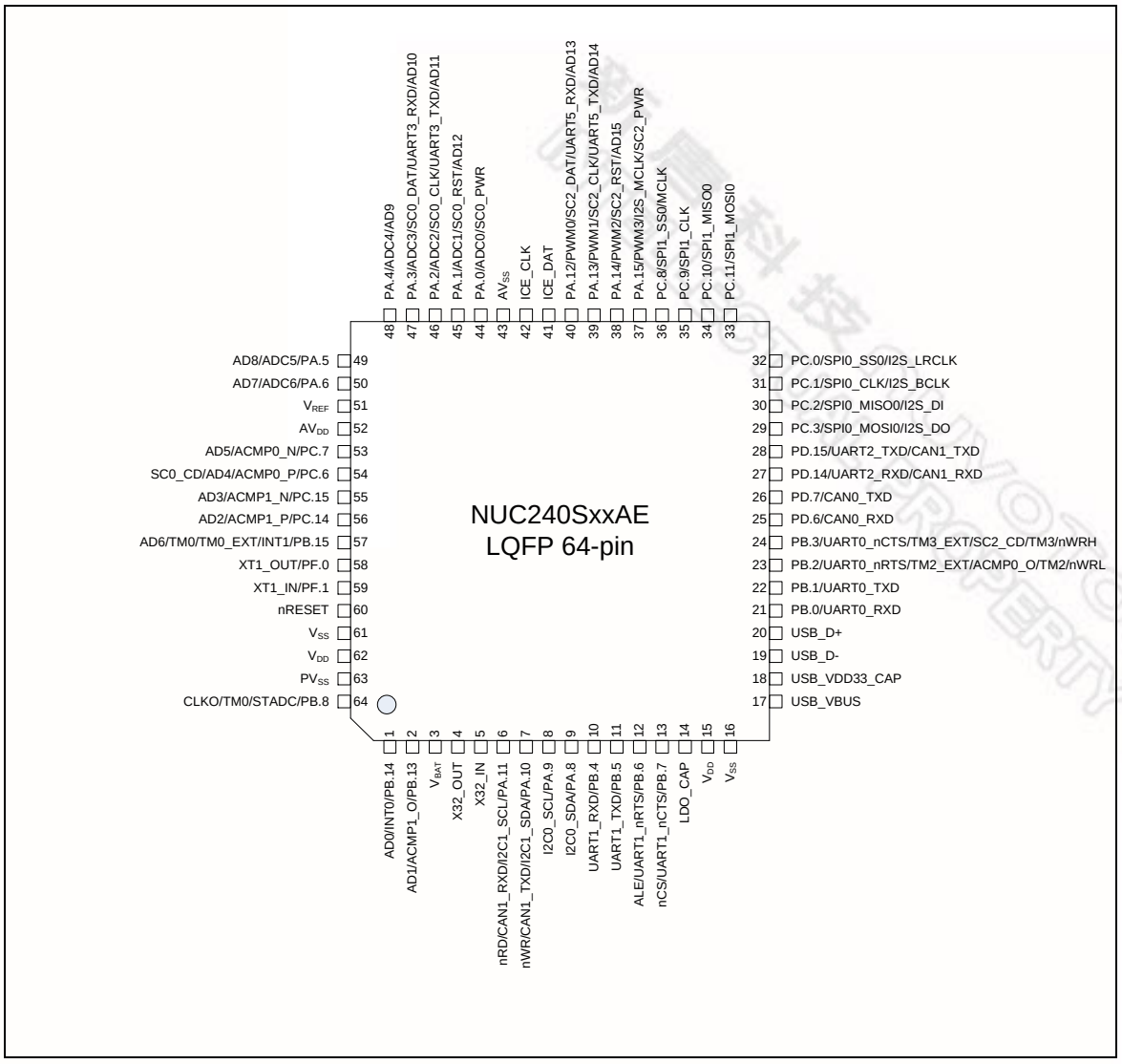

Figure 4-6 NuMicro™ NUC240SxxAE LQFP 64-pin Diagram

4.2.2.3 NuMicro™ NUC240LxxAE LQFP 48 pin

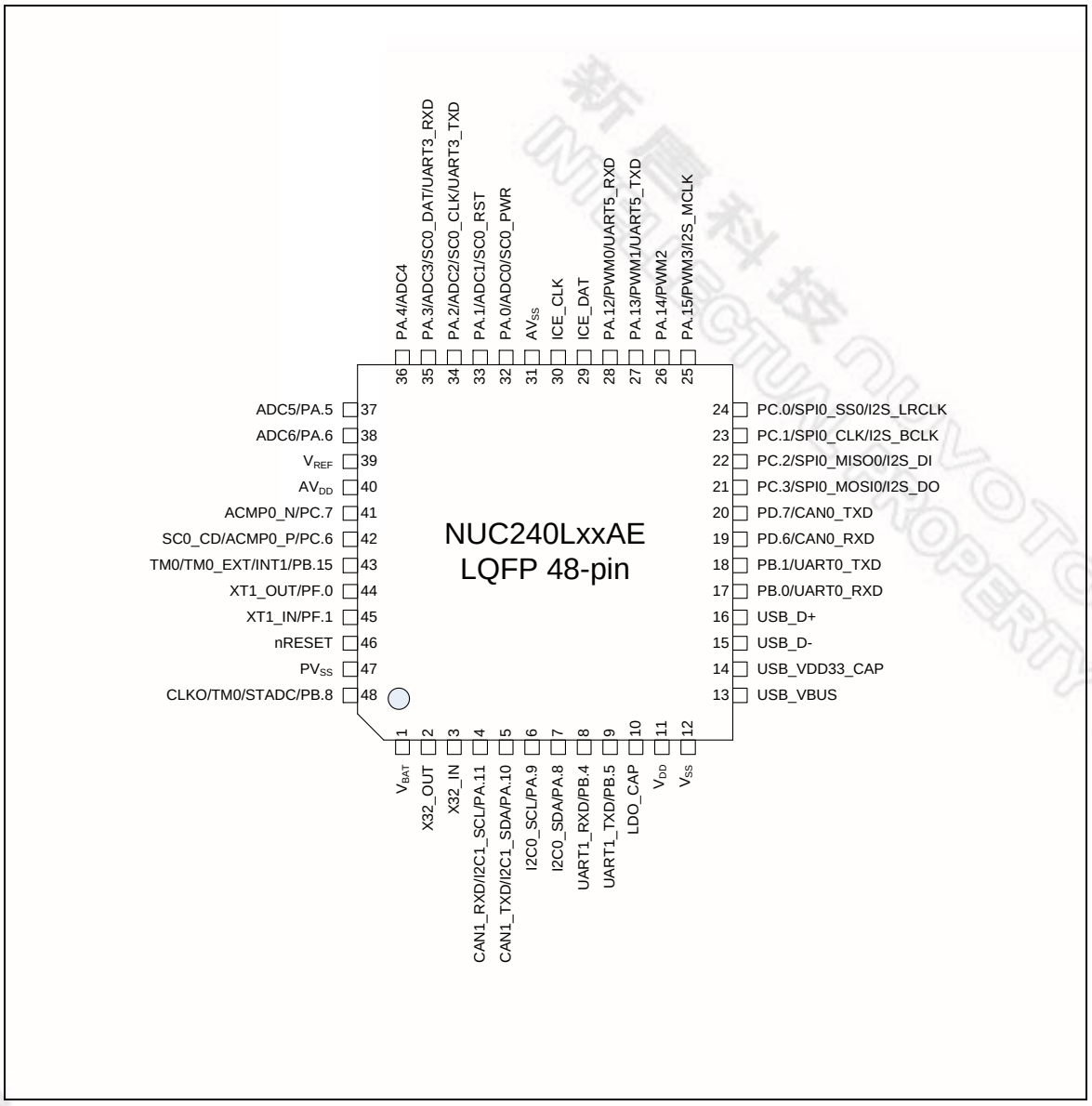

Figure 4-7 NuMicro™ NUC240LxxAE LQFP 48-pin Diagram

4.3 Pin Description

4.3.1 NuMicro™ NUC230 Pin Description

Pin No.			Pin Name	Pin Type	Description
LQFP 100-pin	LQFP 64-pin	LQFP 48-pin			
1			PE.15	I/O	General purpose digital I/O pin.
2			PE.14	I/O	General purpose digital I/O pin.
3			PE.13	I/O	General purpose digital I/O pin.
4	1		PB.14	I/O	General purpose digital I/O pin.
			AD0	I/O	EBI Address/Data bus bit0
			INT0	I	External interrupt0 input pin.
			SPI3_SS1	I/O	2nd SPI3 slave select pin.
5	2		PB.13	I/O	General purpose digital I/O pin.
			AD1	I/O	EBI Address/Data bus bit1
			ACMP1_O	O	Comparator1 output pin.
6	3	1	V_{BAT}	P	Power supply by batteries for RTC.
7	4	2	X32_OUT	O	External 32.768 kHz (low speed) crystal output pin.
8	5	3	X32_IN	I	External 32.768 kHz (low speed) crystal input pin.
9	6	4	PA.11	I/O	General purpose digital I/O pin.
			I2C1_SCL	I/O	I^2C1 clock pin.
			CAN1_RXD	I	Data receiver input pin for CAN1.
			nRD	O	EBI read enable output pin
10	7	5	PA.10	I/O	General purpose digital I/O pin.
			I2C1_SDA	I/O	I^2C1 data input/output pin.
			CAN1_TXD	O	Data transmitter output pin for CAN1.
			nWR	O	EBI write enable output pin
11	8	6	PA.9	I/O	General purpose digital I/O pin.
			I2C0_SCL	I/O	I^2C0 clock pin.
12	9	7	PA.8	I/O	General purpose digital I/O pin.
			I2C0_SDA	I/O	I^2C0 data input/output pin.
13			PD.8	I/O	General purpose digital I/O pin.
			SPI3_SS0	I/O	1st SPI3 slave select pin.
14			PD.9	I/O	General purpose digital I/O pin.
			SPI3_CLK	I/O	SPI3 serial clock pin.
15			PD.10	I/O	General purpose digital I/O pin.

Pin No.			Pin Name	Pin Type	Description
LQFP 100-pin	LQFP 64-pin	LQFP 48-pin			
			TM2_EXT	I	Timer2 external capture input pin.
			ACMP0_O	O	Comparator0 output pin.
			nWRL	O	EBI low byte write enable output pin
35	20	16	PB.3	I/O	General purpose digital I/O pin.
			UART0_nCTS	I	Clear to Send input pin for UART0.
			TM3_EXT	I	Timer3 external capture input pin.
			SC2_CD	I	SmartCard2 card detect pin.
			nWRH	O	EBI high byte write enable output pin
36	21	17	PD.6	I/O	General purpose digital I/O pin.
			CAN0_RXD	I	Data receiver input pin for CAN0.
37	22	18	PD.7	I/O	General purpose digital I/O pin.
			CAN0_TXD	O	Data transmitter output pin for CAN0.
38	23	19	PD.14	I/O	General purpose digital I/O pin.
			UART2_RXD	I	Data receiver input pin for UART2.
			CAN1_RXD	I	Data receiver input pin for CAN1.
39	24	20	PD.15	I/O	General purpose digital I/O pin.
			UART2_TXD	O	Data transmitter output pin for UART2.
			CAN1_TXD	O	Data transmitter output pin for CAN1.
40			PC.5	I/O	General purpose digital I/O pin.
			SPI0_MOSI1	I/O	2nd SPI0 MOSI (Master Out, Slave In) pin.
41			PC.4	I/O	General purpose digital I/O pin.
			SPI0_MISO1	I/O	2nd SPI0 MISO (Master In, Slave Out) pin.
42	25	21	PC.3	I/O	General purpose digital I/O pin.
			SPI0_MOSI0	I/O	1st SPI0 MOSI (Master Out, Slave In) pin.
			I2S_DO	O	I2S data output.
43	26	22	PC.2	I/O	General purpose digital I/O pin.
			SPI0_MISO0	I/O	1st SPI0 MISO (Master In, Slave Out) pin.
			I2S_DI	I	I2S data input.
44	27	23	PC.1	I/O	General purpose digital I/O pin.
			SPI0_CLK	I/O	SPI0 serial clock pin.
			I2S_BCLK	I/O	I2S bit clock pin.
45	28	24	PC.0	I/O	General purpose digital I/O pin.

Pin No.			Pin Name	Pin Type	Description
LQFP 100-pin	LQFP 64-pin	LQFP 48-pin			
60	35		PC.9	I/O	General purpose digital I/O pin.
			SPI1_CLK	I/O	SPI1 serial clock pin.
61	36		PC.8	I/O	General purpose digital I/O pin.
			MCLK	O	EBI clock output
			SPI1_SS0	I/O	1st SPI1 slave select pin.
62	37	25	PA.15	I/O	General purpose digital I/O pin.
			PWM3	I/O	PWM3 output/Capture input.
			I2S_MCLK	O	I2S master clock output pin.
			SC2_PWR	O	SmartCard2 power pin.
63	38	26	PA.14	I/O	General purpose digital I/O pin.
			PWM2	I/O	PWM2 output/Capture input.
			AD15	I/O	EBI Address/Data bus bit15
			SC2_RST	O	SmartCard2 reset pin.
64	39	27	PA.13	I/O	General purpose digital I/O pin.
			PWM1	I/O	PWM1 output/Capture input.
			AD14	I/O	EBI Address/Data bus bit14
			SC2_CLK	O	SmartCard2 clock pin.
		27	UART5_TXD	O	Data transmitter output pin for UART5.
65	40	28	PA.12	I/O	General purpose digital I/O pin.
			PWM0	I/O	PWM0 output/Capture input.
			AD13	I/O	EBI Address/Data bus bit13
			SC2_DAT	O	SmartCard2 data pin.
		28	UART5_RXD	I	Data receiver input pin for UART5.
66	41	29	ICE_DAT	I/O	Serial wire debugger data pin.
67	42	30	ICE_CLK	I	Serial wire debugger clock pin.
68			V_{DD}	P	Power supply for I/O ports and LDO source for internal PLL and digital circuit.
69			V_{SS}	P	Ground pin for digital circuit.
70	43	31	AV_{SS}	AP	Ground pin for analog circuit.
71	44	32	PA.0	I/O	General purpose digital I/O pin.
			ADC0	AI	ADC0 analog input.
			SC0_PWR	O	SmartCard0 power pin.
72	45	33	PA.1	I/O	General purpose digital I/O pin.

Pin No.			Pin Name	Pin Type	Description
LQFP 100-pin	LQFP 64-pin	LQFP 48-pin			
79	51	39	V_{REF}	**AP**	Voltage reference input for ADC.
80	52	40	AV_{DD}	**AP**	Power supply for internal analog circuit.
81			PD.0	**I/O**	General purpose digital I/O pin.
			SPI2_SS0	**I/O**	1st SPI2 slave select pin.
82			PD.1	**I/O**	General purpose digital I/O pin.
			SPI2_CLK	**I/O**	SPI2 serial clock pin.
83			PD.2	**I/O**	General purpose digital I/O pin.
			SPI2_MISO0	**I/O**	1st SPI2 MISO (Master In, Slave Out) pin.
84			PD.3	**I/O**	General purpose digital I/O pin.
			SPI2_MOSI0	**I/O**	1st SPI2 MOSI (Master Out, Slave In) pin.
85			PD.4	**I/O**	General purpose digital I/O pin.
			SPI2_MISO1	**I/O**	2nd SPI2 MISO (Master In, Slave Out) pin.
86			PD.5	**I/O**	General purpose digital I/O pin.
			SPI2_MOSI1	**I/O**	2nd SPI2 MOSI (Master Out, Slave In) pin.
87	53	41	PC.7	**I/O**	General purpose digital I/O pin.
			ACMP0_N	**AI**	Comparator0 negative input pin.
			AD5	**I/O**	EBI Address/Data bus bit5
			SC1_CD	**I**	SmartCard1 card detect pin.
88	54	42	PC.6	**I/O**	General purpose digital I/O pin.
			ACMP0_P	**AI**	Comparator0 positive input pin.
			SC0_CD	**I**	SmartCard0 card detect pin.
			AD4	**I/O**	EBI Address/Data bus bit4
89	55		PC.15	**I/O**	General purpose digital I/O pin.
			AD3	**I/O**	EBI Address/Data bus bit3
			ACMP1_N	**AI**	Comparator1 negative input pin.
90	56		PC.14	**I/O**	General purpose digital I/O pin.
			AD2	**I/O**	EBI Address/Data bus bit2
			ACMP1_P	**AI**	Comparator1 positive input pin.
91	57	43	PB.15	**I/O**	General purpose digital I/O pin.
			INT1	**I**	External interrupt1 input pin.
			TM0_EXT	**I**	Timer 0 external capture input pin.
			TM0	**O**	Timer0 toggle output pin.
			AD6	**I/O**	EBI Address/Data bus bit6

Pin No.			Pin Name	Pin Type	Description
LQFP 100-pin	LQFP 64-pin	LQFP 48-pin			
92	58	44	PF.0	**I/O**	General purpose digital I/O pin.
			XT1_OUT	**O**	External 4~24 MHz (high speed) crystal output pin.
93	59	45	PF.1	**I/O**	General purpose digital I/O pin.
			XT1_IN	**I**	External 4~24 MHz (high speed) crystal input pin.
94	60	46	nRESET	**I**	External reset input: active LOW, with an internal pull-up. Set this pin low reset chip to initial state.
95	61		V_{SS}	**P**	Ground pin for digital circuit.
96	62		V_{DD}	**P**	Power supply for I/O ports and LDO source for internal PLL and digital circuit.
97			PF.2	**I/O**	General purpose digital I/O pin.
			PS2_DAT	**I/O**	PS/2 data pin.
98			PF.3	**I/O**	General purpose digital I/O pin.
			PS2_CLK	**I/O**	PS/2 clock pin.
99	63	47	PV_{SS}	**P**	PLL ground.
100	64	48	PB.8	**I/O**	General purpose digital I/O pin.
			STADC	**I**	ADC external trigger input.
			TM0	**I/O**	Timer0 event counter input / toggle output.
			CLKO	**O**	Frequency divider clock output pin.

Note: Pin Type I = Digital Input, O = Digital Output; AI = Analog Input; P = Power Pin; AP = Analog Power

31	15	**SPI1_INT**	SPI1	SPI1 interrupt
32	16	**SPI2_INT**	SPI2	SPI2 interrupt
33	17	**SPI3_INT**	SPI3	SPI3 interrupt
34	18	**I2C0_INT**	I^2C0	I^2C0 interrupt
35	19	**I2C1_INT**	I^2C1	I^2C1 interrupt
36	20	**-**	-	Reserved
37	21	**-**	-	Reserved
38	22	**SC012_INT**	SC0/1/2	SC0, SC1 and SC2 interrupt
39	23	**USB_INT**	USBD	USB 2.0 FS Device interrupt
40	24	**PS2_INT**	PS/2	PS/2 interrupt
41	25	**ACMP_INT**	ACMP	Analog Comparator interrupt
42	26	**PDMA_INT**	PDMA	PDMA interrupt
43	27	**I2S_INT**	I^2S	I^2S interrupt
44	28	**PWRWU_INT**	CLKC	Clock controller interrupt for chip wake-up from Power-down state
45	29	**ADC_INT**	ADC	ADC interrupt
46	30	**IRC_INT**	IRC	IRC TRIM interrupt
47	31	**RTC_INT**	RTC	Real Time Clock interrupt

Table 6-3 System Interrupt Map

6.2.6.2 Vector Table

When an interrupt is accepted, the processor will automatically fetch the starting address of the interrupt service routine (ISR) from a vector table in memory. For ARMv6-M, the vector table base address is fixed at 0x00000000. The vector table contains the initialization value for the stack pointer on reset, and the entry point addresses for all exception handlers. The vector number on previous page defines the order of entries in the vector table associated with exception handler entry as illustrated in previous section.

Vector Table Word Offset	Description
0	SP_main – The Main stack pointer
Vector Number	Exception Entry Pointer using that Vector Number

Table 6-4 Vector Table Format

6.2.6.3 Operation Description

NVIC interrupts can be enabled and disabled by writing to their corresponding Interrupt Set-Enable or Interrupt Clear-Enable register bit-field. The registers use a write-1-to-enable and write-1-to-clear policy, both registers reading back the current enabled state of the corresponding interrupts. When an interrupt is disabled, interrupt assertion will cause the interrupt to become Pending, however, the interrupt will not activate. If an interrupt is Active when it is disabled, it remains in its Active state until cleared by reset or an exception return. Clearing the enable bit prevents new activations of the associated interrupt.

NVIC interrupts can be pended/un-pended using a complementary pair of registers to those used to enable/disable the interrupts, named the Set-Pending Register and Clear-Pending Register respectively. The registers use a write-1-to-enable and write-1-to-clear policy, both registers reading back the current pended state of the corresponding interrupts. The Clear-Pending Register has no effect on the execution status of an Active interrupt.

NVIC interrupts are prioritized by updating an 8-bit field within a 32-bit register (each register supporting four interrupts).

The general registers associated with the NVIC are all accessible from a block of memory in the System Control Space and will be described in next section.

6.2.7 System Control

The Cortex™-M0 status and operating mode control are managed by System Control Registers. Including CPUID, Cortex™-M0 interrupt priority and Cortex™-M0 power management can be controlled through these system control registers.

For more detailed information, please refer to the “ARM® Cortex™-M0 Technical Reference Manual” and “ARM® v6-M Architecture Reference Manual”.

6.6 General Purpose I/O (GPIO)

6.6.1 Overview

The NuMicro™ NUC230/240 series has up to 84 General Purpose I/O pins to be shared with other function pins depending on the chip configuration. These 84 pins are arranged in 6 ports named as GPIOA, GPIOB, GPIOC, GPIOD, GPIOE and GPIOF. The GPIOA/B/C/D/E port has the maximum of 16 pins and GPIOF port has the maximum of 4 pins. Each of the 84 pins is independent and has the corresponding register bits to control the pin mode function and data.

The I/O type of each of I/O pins can be configured by software individually as input, output, open-drain or Quasi-bidirectional mode. After reset, the I/O mode of all pins are depending on Config0[10] setting. In Quasi-bidirectional mode, I/O pin has a very weak individual pull-up resistor which is about 110~300 KΩ for V_{DD} is from 5.0 V to 2.5 V.

6.6.2 Features

- Four I/O modes:
  - Quasi-bidirectional
  - Push-Pull output
  - Open-Drain output
  - Input only with high impendence
- TTL/Schmitt trigger input selectable by GPx_TYPE[15:0] in GPx_MFP[31:16]
- I/O pin configured as interrupt source with edge/level setting
- Configurable default I/O mode of all pins after reset by Config0[10] setting
  - If Config[10] is 0, all GPIO pins in input tri-state mode after chip reset
  - If Config[10] is 1, all GPIO pins in Quasi-bidirectional mode after chip reset
- I/O pin internal pull-up resistor enabled only in Quasi-bidirectional I/O mode
- Enabling the pin interrupt function will also enable the pin wake-up function.

6.7 PDMA Controller (PDMA)

6.7.1 Overview

The NuMicro™ NUC230/240 series DMA contains nine-channel peripheral direct memory access (PDMA) controller and a cyclic redundancy check (CRC) generator.

The PDMA that transfers data to and from memory or transfer data to and from APB devices. For PDMA channel (PDMA CH0~CH8), there is one-word buffer as transfer buffer between the Peripherals APB devices and Memory. Software can stop the PDMA operation by disable PDMA PDMACEN (PDMA_CSRx[0]). The CPU can recognize the completion of a PDMA operation by software polling or when it receives an internal PDMA interrupt. The PDMA controller can increase source or destination address or fixed them as well.

The DMA controller contains a cyclic redundancy check (CRC) generator that can perform CRC calculation with programmable polynomial settings. The CRC engine supports CPU PIO mode and DMA transfer mode.

6.8.2 Features

- Four sets of 32-bit timers with 24-bit up counter and one 8-bit prescale counter
- Independent clock source for each timer
- Provides four timer counting modes: one-shot, periodic, toggle and continuous counting
- Time-out period = (Period of timer clock input) * (8-bit prescale counter + 1) * (24-bit TCMP)
- Maximum counting cycle time = (1 / T MHz) * (2^8) * (2^{24}), T is the period of timer clock
- 24-bit up counter value is readable through TDR (Timer Data Register)
- Supports event counting function to count the event from external counter pin (TM0~TM3)
- Supports external pin capture (TM0_EXT~TM3_EXT) for interval measurement
- Supports external pin capture (TM0_EXT~TM3_EXT) for reset 24-bit up counter
- Supports chip wake-up from Idle/Power-down mode if a timer interrupt signal is generated

6.19 USB Device Controller (USBD)

6.19.1 Overview

There is one set of USB 2.0 full-speed device controller and transceiver in this device. It is compliant with USB 2.0 full-speed device specification and supports control/bulk/interrupt/ isochronous transfer types.

In this device controller, there are two main interfaces: the APB bus and USB bus which comes from the USB PHY transceiver. For the APB bus, the CPU can program control registers through it. There are 512 bytes internal SRAM as data buffer in this controller. For IN or OUT transfer, it is necessary to write data to SRAM or read data from SRAM through the APB interface or SIE. User needs to set the effective starting address of SRAM for each endpoint buffer through “buffer segmentation register (USB_BUFSEGx)”.

There are 8 endpoints in this controller. Each of the endpoint can be configured as IN or OUT endpoint. All the operations including Control, Bulk, Interrupt and Isochronous transfer are implemented in this block. The block of “Endpoint Control” is also used to manage the data sequential synchronization, endpoint states, current start address, transaction status, and data buffer status for each endpoint.

There are four different interrupt events in this controller. They are the wake-up function, device plug-in or plug-out event, USB events, and BUS events. Any event will cause an interrupt, and users just need to check the related event flags in interrupt event status register (USB_INTSTS) to acknowledge what kind of interrupt occurring, and then check the related USB Endpoint Status Register (USB_EPSTS) to acknowledge what kind of event occurring in this endpoint.

A software-disconnect function is also supported for this USB controller. It is used to simulate the disconnection of this device from the host. If DRVSE0 (USB_DRVSE0[0]) is set to 1, the USB controller will force the output of USB_D+ and USB_D- to level low. After DRVSE0 bit is cleared to 0, host will enumerate the USB device again.

Please refer to *Universal Serial Bus Specification Revision 1.1* for details.

6.19.2 Features

- Compliant with USB 2.0 Full-Speed specification
- Provides 1 interrupt vector with 4 different interrupt events (WAKEUP, FLDET, USB and BUS)
- Supports Control/Bulk/Interrupt/Isochronous transfer type
- Supports suspend function when no bus activity existing for 3 ms
- Provides 8 endpoints for configurable Control/Bulk/Interrupt/Isochronous transfer types and maximum 512 bytes buffer size
- Provides remote wake-up capability

PARAMETER	SYM.	SPECIFICATION				TEST CONDITIONS
		MIN.	TYP.	MAX.	UNIT	
Hysteresis voltage of PA, PB, PC, PD,PE, PF (Schmitt input)	V_{HY}		$0.2V_{DD}$		V	
Input Low Voltage XT1_IN[*2]	V_{IL3}	0	-	0.8	V	V_{DD} = 4.5V
		0	-	0.4		V_{DD} = 3.0V
Input High Voltage XT1_IN[*2]	V_{IH3}	3.5	-	V_{DD} +0.2	V	V_{DD} = 5.5V
		2.4	-	V_{DD} +0.2		V_{DD} = 3.0V
Input Low Voltage X32I[*2]	V_{IL4}	0	-	0.4	v	
Input High Voltage X32I[*2]	V_{IH4}	1.2		1.8	V	
Negative going threshold (Schmitt input), /RESET	V_{ILS}	-0.5	-	$0.2V_{DD}$ -0.2	V	
Positive going threshold (Schmitt input), /RESET	V_{IHS}	$0.7V_{DD}$	-	V_{DD} +0.5	V	
Source Current PA, PB, PC, PD, PE, PF (Quasi-bidirectional Mode)	I_{SR11}	-300	-370	-450	µA	V_{DD} = 4.5V, V_S = 2.4V
	I_{SR12}	-50	-70	-90	µA	V_{DD} = 2.7V, V_S = 2.2V
	I_{SR12}	-40	-60	-80	µA	V_{DD} = 2.5V, V_S = 2.0V
Source Current PA, PB, PC, PD, PE, PF (Push-pull Mode)	I_{SR21}	-24	-28	-32	mA	V_{DD} = 4.5V, V_S = 2.4V
	I_{SR22}	-4	-6	-8	mA	V_{DD} = 2.7V, V_S = 2.2V
	I_{SR22}	-3	-5	-7	mA	V_{DD} = 2.5V, V_S = 2.0V
Sink Current PA, PB, PC, PD, PE, PF (Quasi-bidirectional and Push-pull Mode)	I_{SK1}	10	16	20	mA	V_{DD} = 4.5V, V_S = 0.45V
	I_{SK1}	7	10	13	mA	V_{DD} = 2.7V, V_S = 0.45V
	I_{SK1}	6	9	12	mA	V_{DD} = 2.5V, V_S = 0.45V
Brown-out Voltage with BOD_VL [1:0] = 00b	$V_{BO2.2}$	2.1	2.2	2.3	V	
Brown-out Voltage with BOD_VL [1:0] = 01b	$V_{BO2.7}$	2.6	2.7	2.8	V	
Brown-out voltage with BOD_VL [1:0] = 10b	$V_{BO3.7}$	3.5	3.7	3.9	V	
Brown-out Voltage with BOD_VL [1:0] = 11b	$V_{BO4.4}$	4.2	4.4	4.6	V	

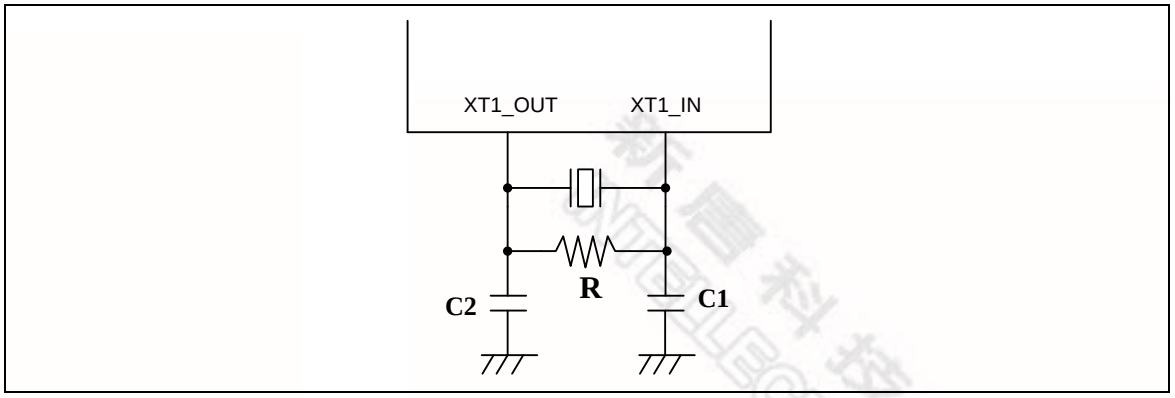

Figure 8-1 Typical Crystal Application Circuit

8.3.3 External 32.768 kHz Low Speed Crystal Oscillator

PARAMETER	CONDITION	MIN.	TYP.	MAX.	UNIT
Operation Voltage V_{DD}	-	2.5	-	5.5	V
Operation Temperature	-	-40	-	105	℃
Operation Current	32.768KHz at V_{DD}=5V		1.6		μA
Clock Frequency	External crystal	-	32.768	-	kHz

8.3.4 Internal 22.1184 MHz High Speed Oscillator

PARAMETER	CONDITION	MIN.	TYP.	MAX.	UNIT
Operation Voltage V_{DD}	-	2.5	-	5.5	V
Center Frequency	-	-	22.1184	-	MHz
Calibrated Internal Oscillator Frequency	+25℃; V_{DD} =5 V	-1	-	+1	%
	-40℃~+105℃; V_{DD}=2.5 V~5.5 V	-3	-	+3	%
Operation Current	V_{DD} =5 V	-	800	-	uA

8.3.5 Internal 10 kHz Low Speed Oscillator

PARAMETER	CONDITION	MIN.	TYP.	MAX.	UNIT
Operation Voltage V_{DD}	-	2.5	-	5.5	V
Center Frequency	-	-	10	-	kHz
Calibrated Internal Oscillator Frequency	+25℃; V_{DD} =5 V	-20	-	+20	%
	-40℃~+105℃; V_{DD}=2.5 V~5.5 V	-50	-	+50	%

8.4.8.4 USB LDO Specification

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V_{BUS}	VBUS Pin Input Voltage		4.0	5.0	5.5	V
V_{DD33}	LDO Output Voltage		3.0	3.3	3.6	V
C_{bp}	External Bypass Capacitor			1.0	-	uF

8.5 Flash DC Electrical Characteristics

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V_{DD}	Supply Voltage		1.62	1.8	1.98	V[2]
N_{ENDUR}	Endurance		10000			cycles[1]
T_{RET}	Data Retention	At 25℃	100			year
T_{ERASE}	Page Erase Time			20		ms
T_{MER}	Mass Erase Time			40		ms
T_{PROG}	Program Time			40		μs
I_{DD1}	Read Current		-	0.15	0.5	mA/MHz
I_{DD2}	Program/Erase Current				7	mA

1. Number of program/erase cycles.
2. V_{DD} is source from chip LDO output voltage.

This table is guaranteed by design, not test in production.